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(71) Applicant (for all designated States except US): **DOW CORNING TORAY SILICONE CO. LTD.** [JP/JP]; 1-3, Marunouchi 1-chome, Chiyoda-ku, Tokyo, 1000005 (JP).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **MORITA, Yoshit-sugu** [JP/JP]; c/o Dow Corning Toray Silicone Co., Ltd., 2-2, Chigusakaigan, Ichihara-shi, Chiba, 2990108 (JP). **MINE, Katsutoshi** [JP/JP]; c/o Dow Corning Toray Silicone Co., Ltd., 2-2, Chigusakaigan, Ichihara-shi, Chiba, 2990108 (JP). **NAKANISHI, Junji** [JP/JP]; c/o Dow

Corning Toray Silicone Co., Ltd., 2-2, Chigusakaigan, Ichihara-shi, Chiba, 2990108 (JP). **ENAMI, Hiroji** [JP/JP]; c/o Dow Corning Toray Silicone Co., Ltd., 2-2, Chigusakaigan, Ichihara-shi, Chiba, 2990108 (JP). **MIYAJIMA, Fumio** [JP/JP]; c/o Apic Yamada Corp., 90 Kamitokuma, Chikuma-shi, Nagano, 3890898 (JP).

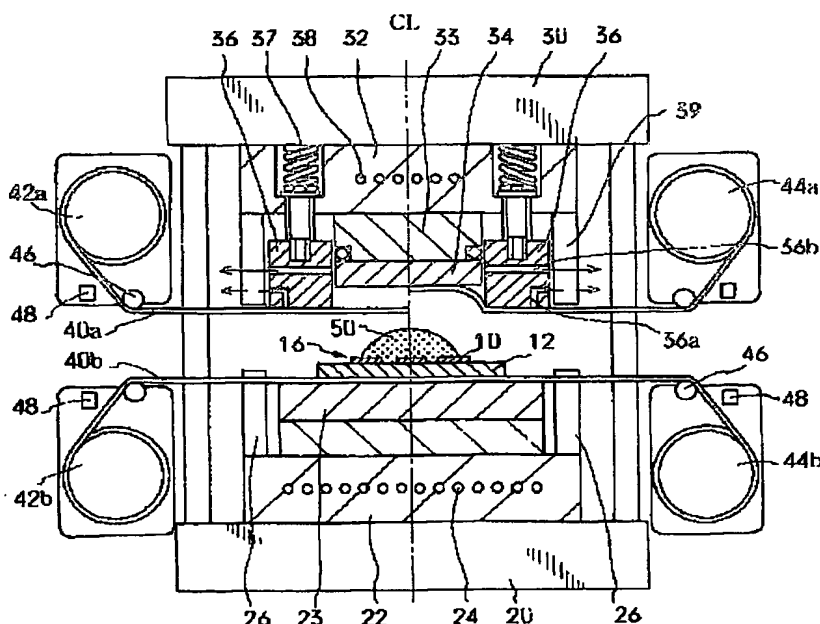
(74) Agent: **KUBOTA, Yoshitaka**; ASA International Patent Firm Chiba Office, 43-27, Satsukigaoka 1-chome, Hanami-gawa-ku, Chiba-shi, Chiba, 2620014 (JP).

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(54) Title: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THEREOF



(57) Abstract: A method of manufacturing a semiconductor device sealed with silicone rubber, characterized by 1) placing an unsealed semiconductor device into a mold, 2) thereafter filling in spaces between the mold and the semiconductor device with a sealing silicone rubber composition, and 3) subjecting the composition to compression molding. By the utilization of this method, a sealed semiconductor device is free of voids, and a thickness of a sealing silicone rubber can be controlled.